



ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES®

Material Composition Declaration

© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item.
Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
<http://www.ipc.org/IPC-175x>

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information

Supplier Information

Company Name * Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	Response Date* Sat, Mar 05, 2011 02:15 AM
Contact Name * David Lancaster	Title - Contact Product Ecology	Phone - Contact * 801-562-7455	Email - Contact * david.lancaster@fairchildsemi.com
Authorized Representative * David Lancaster	Title - Representative Product Ecology	Phone - Representative * 801-562-7455	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
74VCX162245MTD	74VCX162245MTD	TSSOP-48 (NiPdAu)			INTERNAL PENANG	0.192	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Nickel/Palladium/Gold (Ni/Pd/Au)	CU Alloy	2	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration

Declaration Type * Custom

**RoHS Directive
2002/95/EC****RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

RoHS Declaration ***1 - Item(s) does not contain RoHS restricted substances per the definition above****Supplier Acceptance * Accepted**

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC

None

Declaration Signature

Supplier Signature



DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name TSSOP-48 (NiPdAu)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Silicon	2.300	Supplier		Silicon	2.300	7440-21-3	11994
Die Attach	Adhesive	0.272	Supplier		Acrylic Resin	0.071	54208-63-8	369
			Supplier		Silver	0.201	7440-22-4	1048
Encapsulation	Epoxy	111.000	Supplier		Epoxy Resin	16.700	29690-82-2	87087
			Supplier		Silica	94.400	60676-86-0	492278
Lead Frame	Copper Alloy	70.200	Supplier		Copper	67.200	7440-50-8	350435
			Supplier		Magnesium	0.105	7439-95-4	548
			B	Nickel (external applications only)	Nickel	2.110	7440-02-0	11003
			Supplier		Silicon	0.456	7440-21-3	2378
			Supplier		Silver	0.324	7440-22-4	1690
Plating	Pb-Free Solder	6.700	Supplier		Gold	0.127	7440-57-5	662
			B	Nickel (external applications only)	Nickel	6.390	7440-02-0	33323
			Supplier		Palladium	0.188	7440-05-3	980
Wire Bond	Gold Wire	1.190	Supplier		Gold	1.190	7440-57-5	6206